

10/538306

JC20 Rec'd PCT/PTO 09 JUN 2005  
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q88465

Makoto UEKI, et al.

Appln. No.: Not yet assigned

Confirmation No.: Not yet assigned

Group Art Unit: Not yet assigned

Filed: June 9, 2005

Examiner: Not yet assigned

For: COPPER ALLOY FOR WIRING, SEMICONDUCTOR DEVICE, METHOD FOR FORMING WIRING AND METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE

INFORMATION DISCLOSURE STATEMENT  
UNDER 37 C.F.R. §§ 1.97 and 1.98

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In accordance with the duty of disclosure under 37 C.F.R. § 1.56, Applicant hereby notifies the U.S. Patent and Trademark Office of the documents which are listed on the attached PTO/SB/08 A & B (modified) form and/or listed herein and which the Examiner may deem material to patentability of the claims of the above-identified application.

1. Japanese Patent Publication No. 2000-150522, published May 30, 2000, with English abstract.
2. Japanese Patent Publication No. 2001-298084, published October 26, 2001, with English abstract.
3. Japanese Patent Publication No. 2000-208517, published July 28, 2000, with English abstract.

INFORMATION DISCLOSURE STATEMENT  
U.S. National Stage of PCT/JP/2003/12080

4. E.T. Ogawa et al., "Stress-Induced Voiding Under Vias Connected To Wide Cu Metal Leads", *Proceedings of IEEE International Reliability Physics Symposium 2002, USA*, The Electron Device Society and The Reliability Society of the Institute of Electrical and Electronics Engineers, Inc, April 7, 2002, Pages 312-321
5. Japanese Patent Publication No. 11-102909, published April 13, 1999, with English abstract.
6. European Patent Publication No. 0751567, published January 2, 1997.
7. Japanese Patent Publication No. 09-064033, published March 7, 1997, with English abstract.
8. Japanese Patent Publication No. 02-165632, published June 26, 1990, with English abstract.

One copy of each of the listed documents is submitted herewith.

The present Information Disclosure Statement is being filed: (1) No later than three months from the application's filing date; (2) Before the mailing date of the first Office Action on the merits (whichever is later); or (3) Before the mailing date of the first Office Action after filing a request for continued examination (RCE) under §1.114, and therefore, no Statement under 37 C.F.R. § 1.97(e) or fee under 37 C.F.R. § 1.17(p) is required.

In compliance with the concise explanation requirement under 37 C.F.R. § 1.98(a)(3) for foreign language documents, Applicant encloses herewith a copy of the International Search Report issued which cites such documents 5-8. With regards to references 1 - 4, Applicant states

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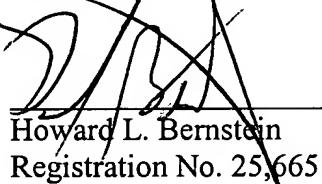
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that above references 1-4 are discussed within the specification beginning at page 4, line 6, page 3, line 15, page 5, line 17 and page 3, line 28, respectively.

The submission of the listed documents is not intended as an admission that any such document constitutes prior art against the claims of the present application. Applicant does not waive any right to take any action that would be appropriate to antedate or otherwise remove any listed document as a competent reference against the claims of the present application.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account. A duplicate copy of this paper is attached.

Respectfully submitted,

  
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WASHINGTON OFFICE  
23373  
CUSTOMER NUMBER

Date: June 9, 2005

Substitute for Form 1449 A & B/PTO		<i>Complete if Known</i>	
<b><u>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</u></b>		10/538306	
(use as many sheets as necessary)		Application Number	Not yet assigned
		Confirmation Number	Not yet assigned
		Filing Date	June 09, 2005
		First Named Inventor	Makoto UEKI
		Art Unit	Not yet assigned
		Examiner Name	Not yet assigned
Sheet	1	of	1
		Attorney Docket Number	
		Q88465	

## **U.S. PATENT DOCUMENTS**

## **FOREIGN PATENT DOCUMENTS**

## **NON PATENT LITERATURE DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city, and/or country where published.	Translation <sup>6</sup>
		E.T. Ogawa et al., "Stress-Induced Voiding Under Vias Connected To Wide Cu Metal Leads", Proceedings of IEEE International Reliability Physics Symposium 2002, USA, The Electron Device Society and The Reliability Society of the Institute of Electrical and Electronics Engineers, Inc, April 7, 2002, Pages 312-321	

<b>Examiner Signature</b>		<b>Date Considered</b>	
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<sup>1</sup>Applicant's unique citation designation number (optional). <sup>2</sup>See Kind Codes of USPTO Patent Documents at [www.uspto.gov](http://www.uspto.gov), MPEP 901.04 or in the comment box of this document. <sup>3</sup> Enter Office that issued the document, by the two-letter code (WIPO Standard ST. 3). <sup>4</sup>For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. <sup>5</sup>Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup>Applicant is to indicate here if English language Translation is attached.

## Prior art(s) for IDS